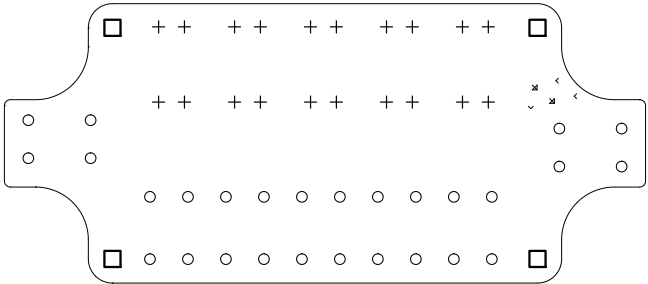


NOTES

- 1.Layers: 2  
2.Thickness: 1.6  
3.Surface finish: HASL (No Lead)  
4.Outer Copper Weight: 2oz  
5.Via covering: Tented  
6.Min hole size: .3mm  
7.Gold Fingers: No  
8.Castellated Holes: No  
9.Edge Plating: No



Drill Map:  
× 0.635mm / 0.0250" (5 holes)  
○ 1.397mm / 0.0550" (28 holes)  
+ 1.600mm / 0.0630" (20 holes)  
□ 3.000mm / 0.1181" (4 holes) (not plated)

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6722 mm
Board overall dimensions:	84.4000 mm x 36.7750 mm		
Min track/spacing:	0.0000 mm / 0.0000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Blue	3.3	0
F.Cu	copper		2.8 mils		1	0
Dielectric 1	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		2.8 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Blue	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0